

Features

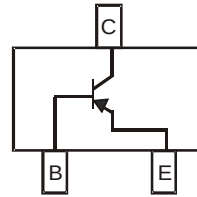
- Epitaxial Planar Die Construction
- Ideal for Medium Power Amplification and Switching
- High Collector Current Rating
- Complementary Version Available (DNBT8105)
- **Lead Free By Design/RoHS Compliant (Note 1)**
- **"Green Device" (Note 2)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound.
UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Finish — Matte Tin annealed over Copper leadframe.
Solderable per MIL-STD-202, Method 208
- Terminal Connections: See Diagram
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.008 grams (approximate)



Top View



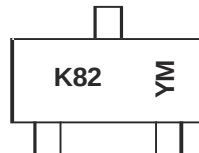
Device Schematic

Ordering Information (Note 3)

Part Number	Case	Packaging
DPBT8105-7	SOT23	3000/Tape & Reel

- Notes:
1. No purposefully added lead.
 2. Diode's Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
 3. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



K82 = Product Type Marking Code
YM = Date Code Marking
Y = Year (ex: S = 2005)
M = Month (ex: 9 = September)

Date Code Key

Year	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015
Code	R	S	T	U	V	W	X	Y	Z	A	B	C
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-80	V
Collector-Emitter Voltage	V _{CEO}	-60	V
Emitter-Base Voltage	V _{EBO}	-5	V
Collector Current - Continuous	I _C	-1	A
Peak Pulse Collector Current	I _{CM}	-2	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 4) @ T _A = 25°C	P _D	600	mW
Thermal Resistance, Junction to Ambient (Note 4) @ T _A = 25°C	R _{θJA}	209	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 5)					
Collector-Base Breakdown Voltage	V _{(BR)CBO}	-80	—	V	I _C = -100μA, I _E = 0
Collector-Emitter Breakdown Voltage	V _{(BR)CEO}	-60	—	V	I _C = -10mA, I _B = 0
Emitter-Base Breakdown Voltage	V _{(BR)EBO}	-5	—	V	I _E = -100μA, I _C = 0
Collector Cutoff Current	I _{CBO}	—	-100	nA	V _{CB} = -60V, I _E = 0
Collector Cutoff Current	I _{CES}	—	-100	nA	V _{CE} = -60V
Emitter Cutoff Current	I _{EBO}	—	-100	nA	V _{EB} = -4V, I _C = 0
ON CHARACTERISTICS (Note 5)					
DC Current Gain	h _{FE}	100	—	—	I _C = -1mA, V _{CE} = -5V
		100	300		I _C = -500mA, V _{CE} = -5V
		80	—		I _C = -1A, V _{CE} = -5V
		30	—		I _C = -2A, V _{CE} = -5V
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	—	-0.3 -0.6	V	I _C = -500mA, I _B = -50mA I _C = -1A, I _B = -100mA
Base-Emitter Saturation Voltage	V _{BE(SAT)}	—	-1.2	V	I _C = -1A, I _B = -100mA
Base-Emitter Turn On Voltage	V _{BE(ON)}	—	-1.0	V	I _C = -1A, V _{CE} = -5V
SMALL SIGNAL CHARACTERISTICS					
Output Capacitance	C _{obo}	—	12	pF	V _{CB} = -10V, f = 1.0MHz
Current Gain-Bandwidth Product	f _T	150	—	MHz	V _{CE} = 10V, I _C = 50mA, f = 100MHz

- Notes:
- Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
 - Short duration pulse test used to minimize self-heating effect.

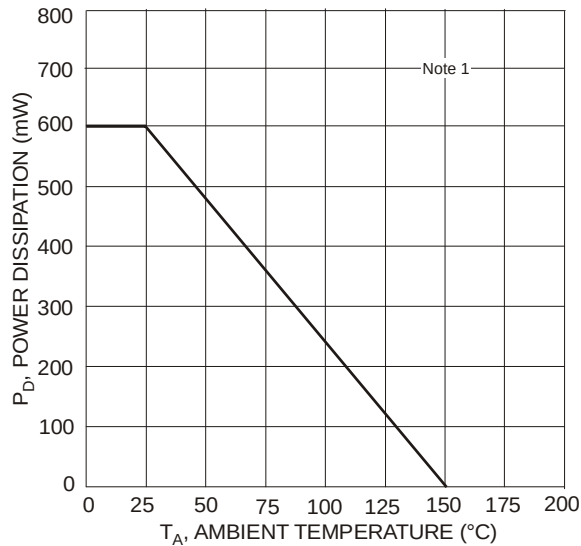


Fig. 1, Max Power Dissipation vs. Ambient Temperature

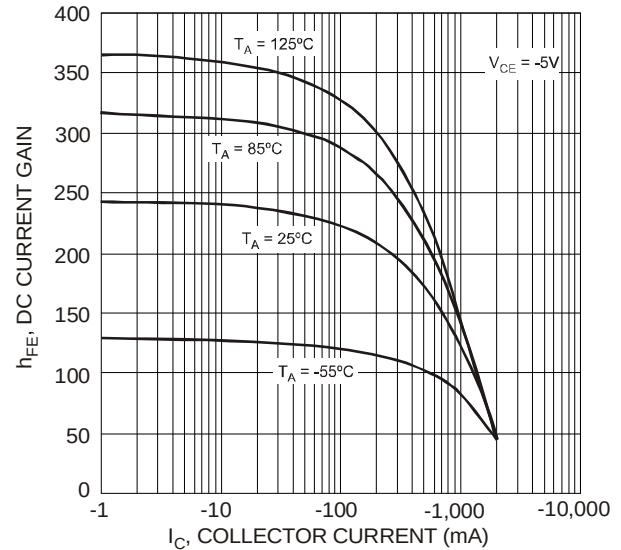


Fig. 2, DC Current Gain vs. Collector Current

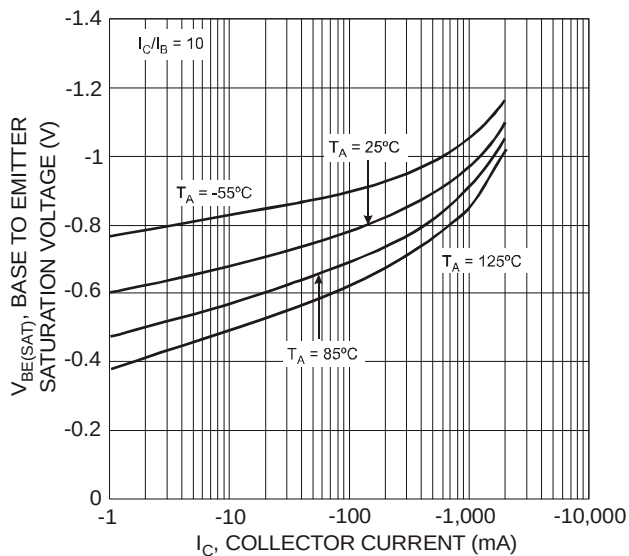


Fig. 3, Base-Emitter Saturation Voltage vs. Collector Current

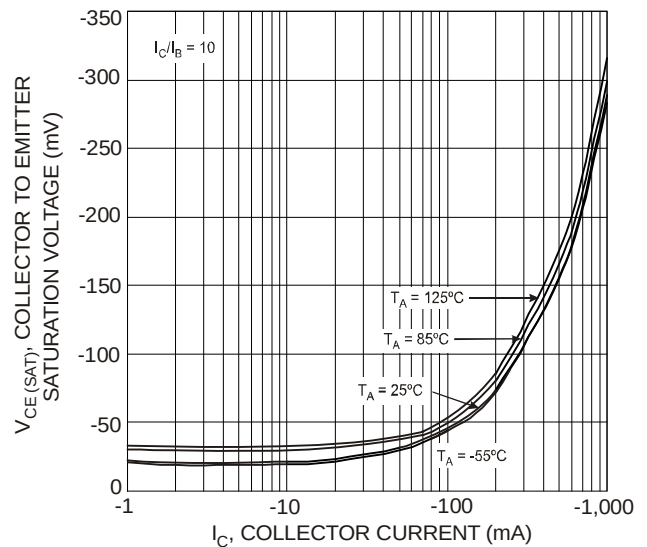


Fig. 4, Collector-Emitter Saturation Voltage vs. Collector Current

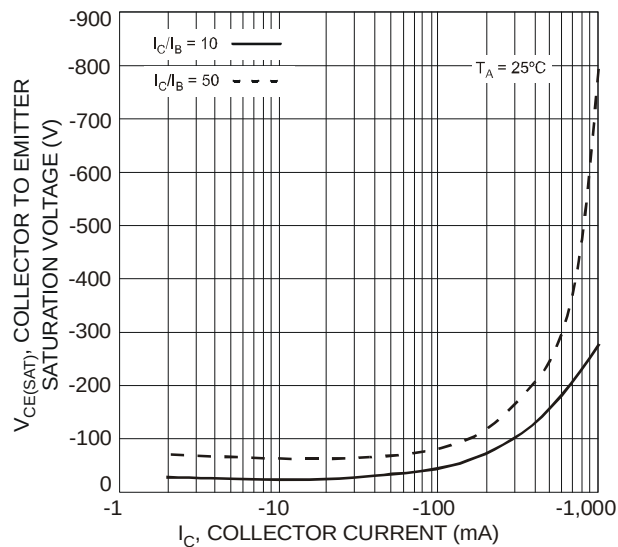


Fig. 5, Collector-Emitter Saturation Voltage vs. Collector Current

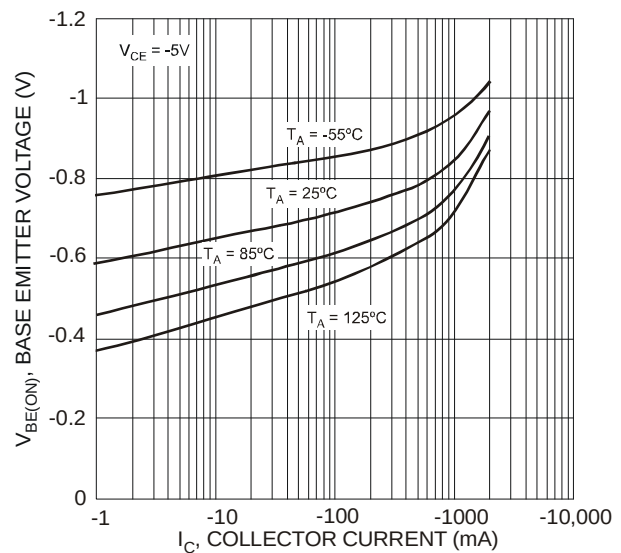


Fig. 6, Base-Emitter Voltage vs. Collector Current

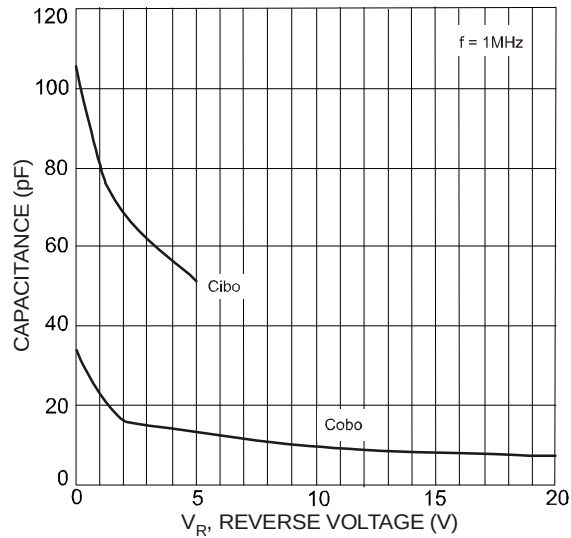
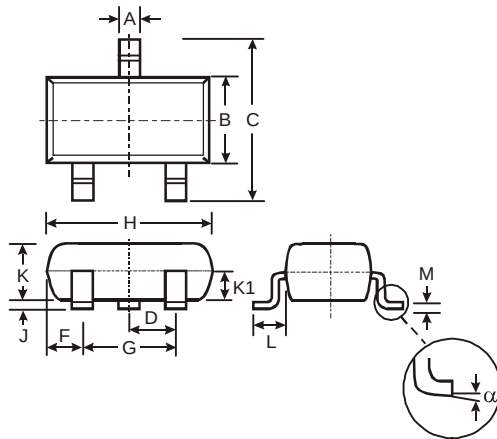


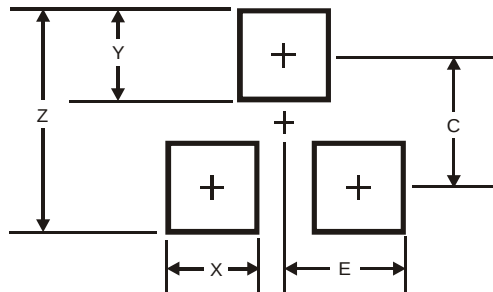
Fig. 7, Capacitance vs. Reverse Voltage

Package Outline Dimensions



SOT-23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.903	1.10	1.00
K1	-	-	0.400
L	0.45	0.61	0.55
M	0.085	0.18	0.11
α	0°	8°	-
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

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